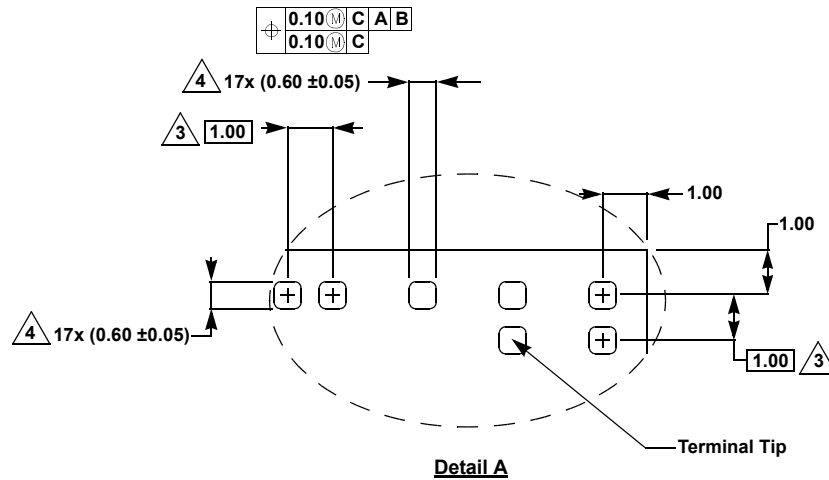
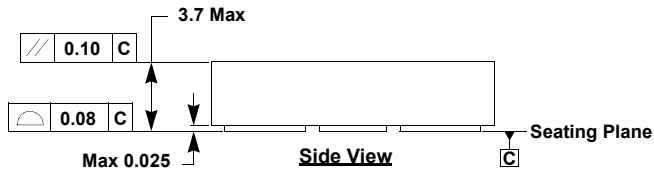
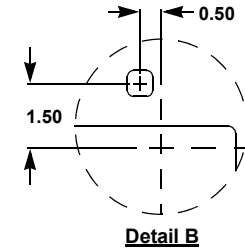
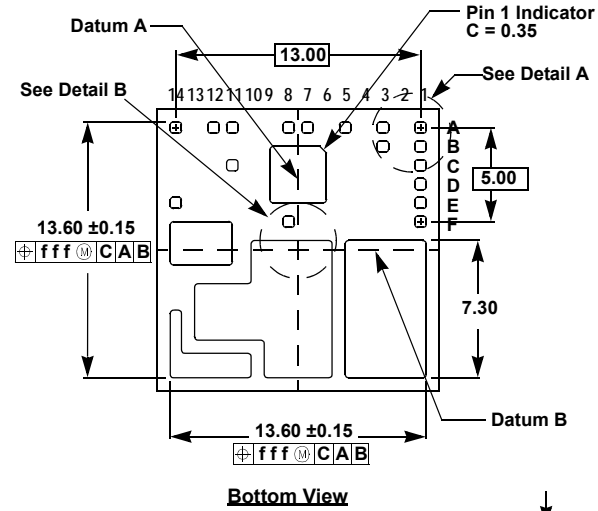
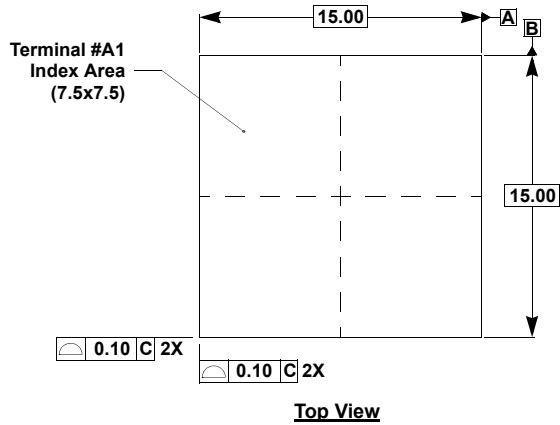


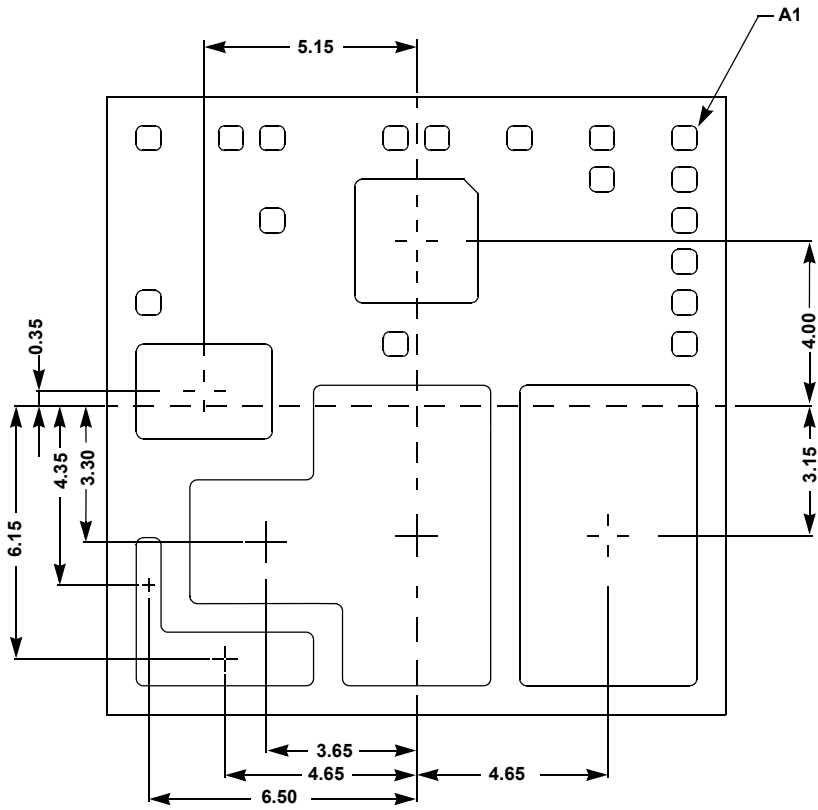
Package Outline Drawing

Y22.15x15
 22 I/O 15mmx15mmx3.6mm Custom HDA Module
 Rev 3, 9/18

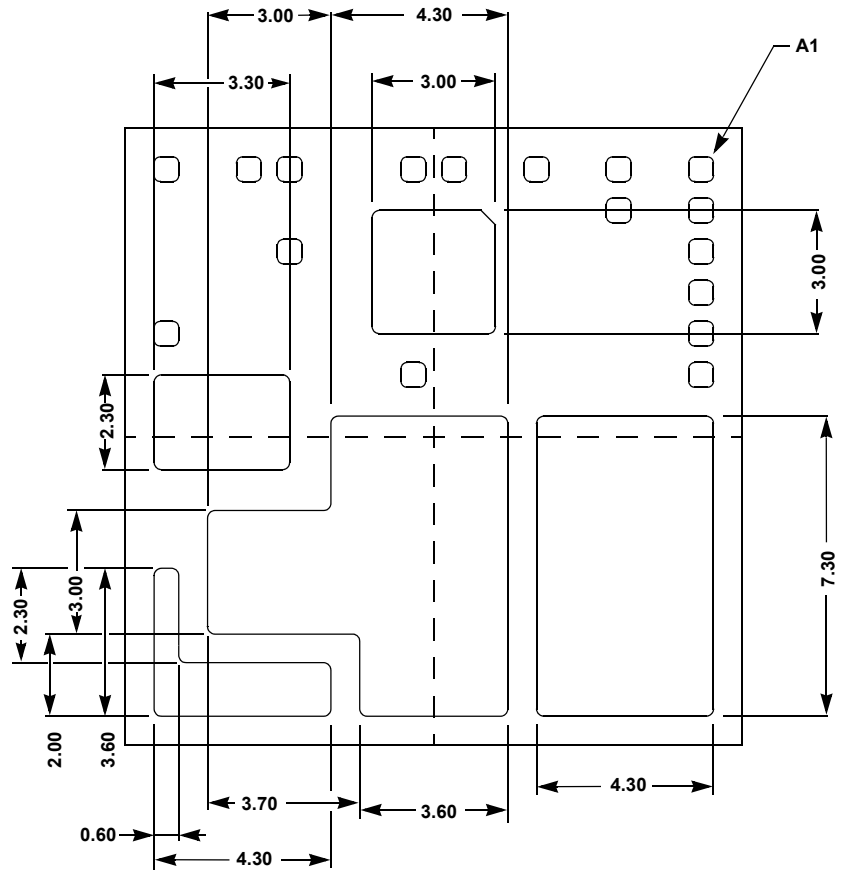


Notes:

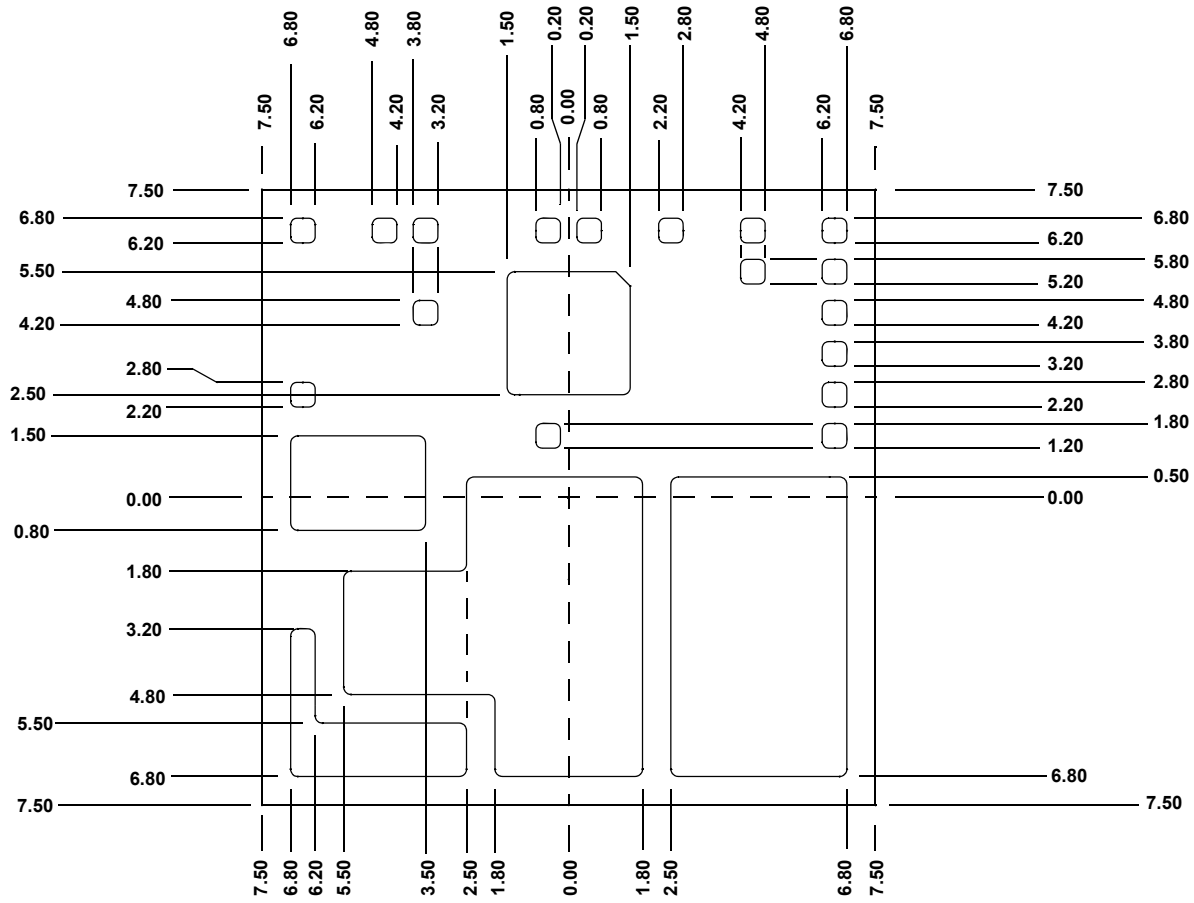
1. All dimensions are in millimeters.
2. All tolerances $\pm 0.10\text{mm}$, unless otherwise noted.
3. Represents the basic land grid pitch.
4. The total number of smaller I/O pads is 17. All 17 I/O's are centered in a fixed row and column matrix at 1.0mm pitch BSC.
5. Dimensioning and tolerancing per ASME Y14.5M-1994.
6. Tolerance for exposed DAP edge location dimension.



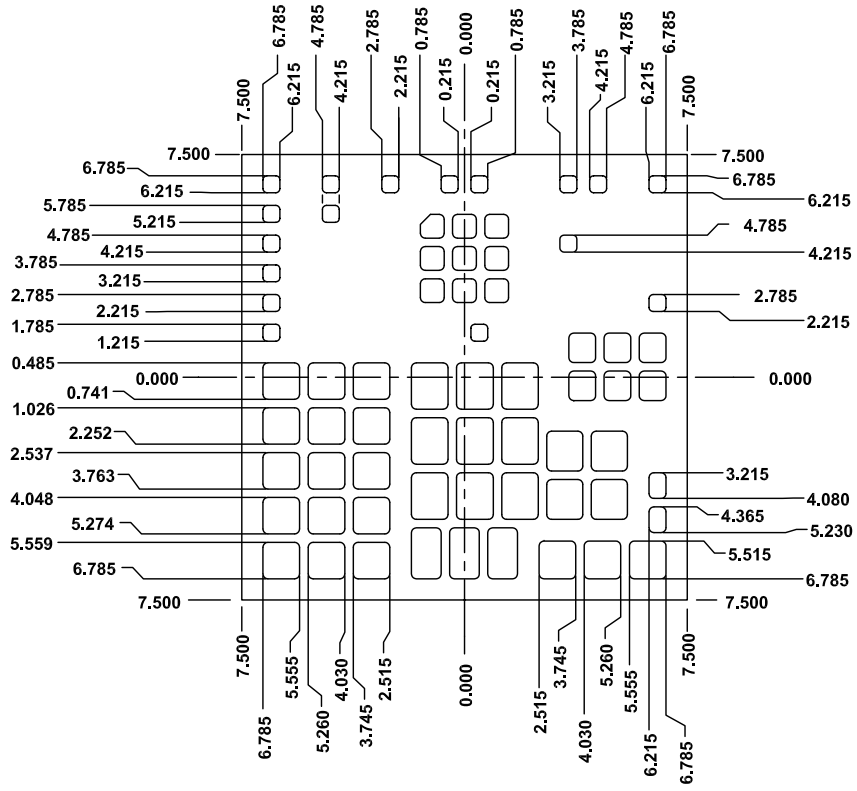
Centerline Position Details for the 5 Exposed DAPs
Bottom View



Dimensional Details for the 5 Exposed PADs
Bottom View

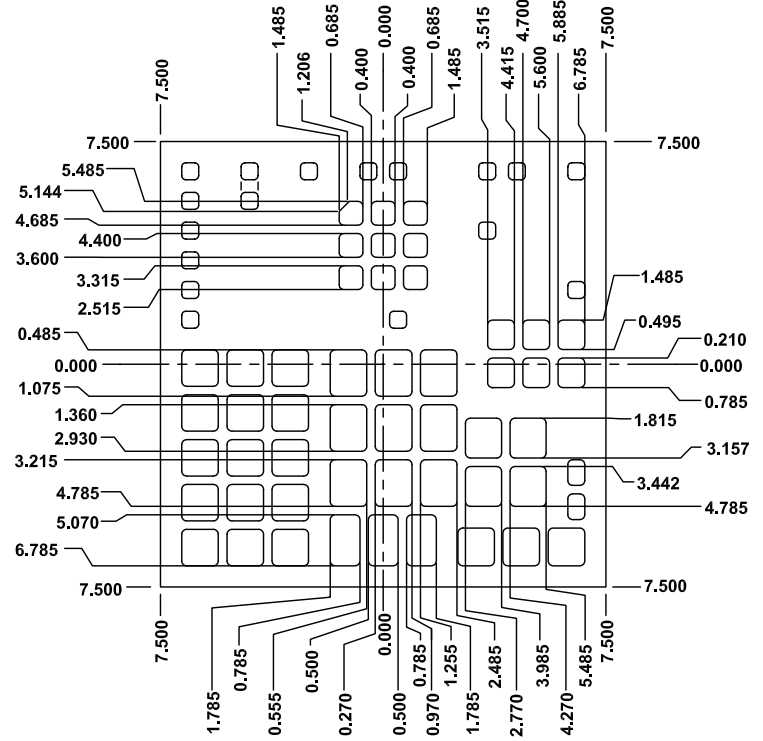


Terminal and Pad Edge Details
Bottom View



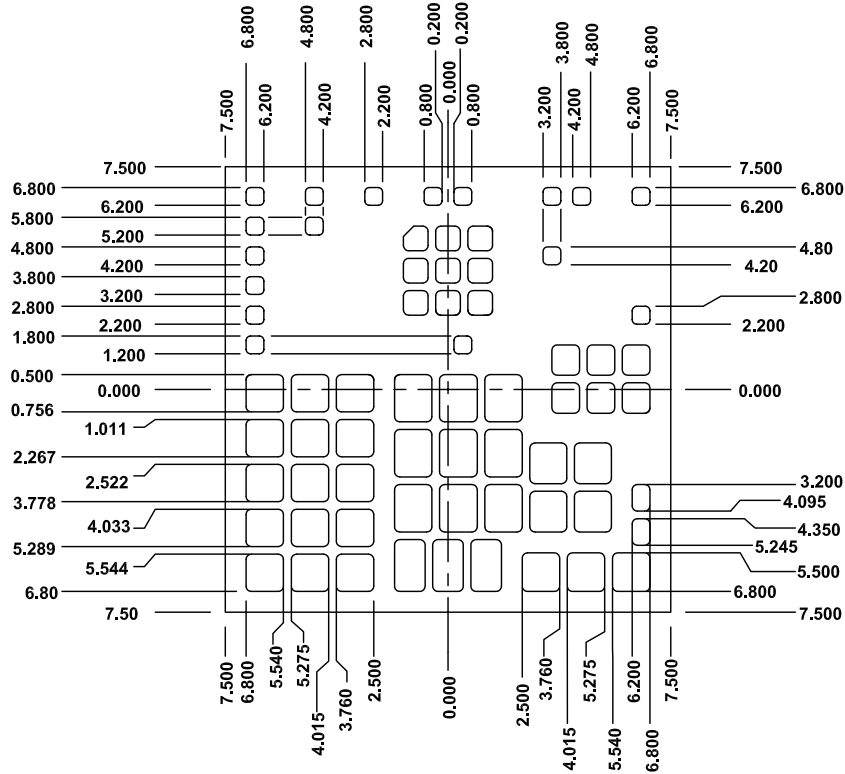
Suggested Stencil Pattern - 1

Top View



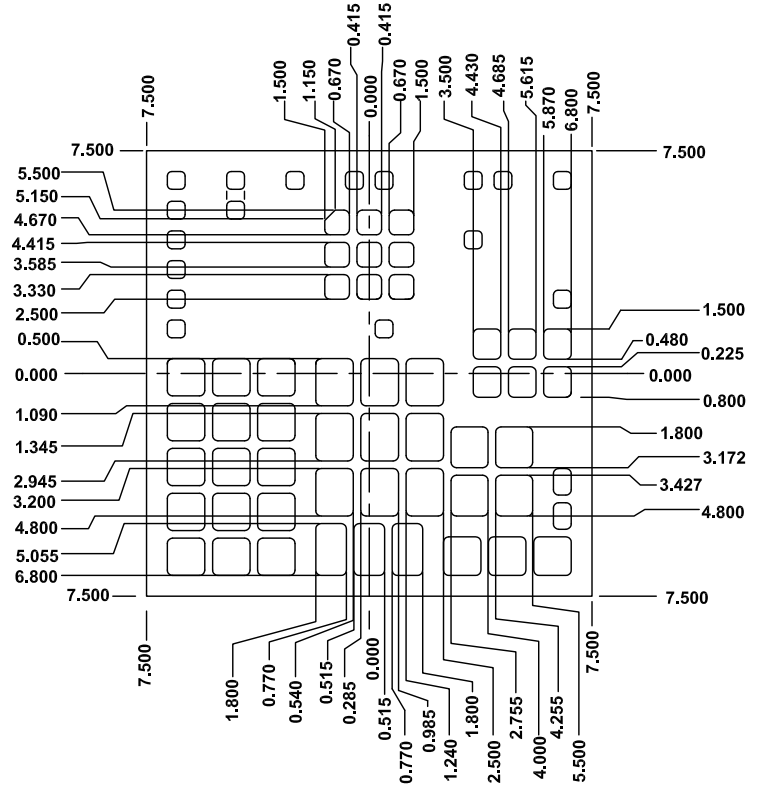
Suggested Stencil Pattern - 2

Top View



Suggested PCB Land Pattern - 1

Top View



Suggested PCB Land Pattern - 2

Top View